

### FEATURES

- High-speed access time: 12, 15, and 20 ns
- CMOS low power operation
  - 450 mW (typical) operating
  - 250  $\mu$ W (typical) standby
- TTL compatible interface levels
- Single 5V  $\pm$  10% power supply
- Fully static operation: no clock or refresh required
- Three state outputs
- Industrial temperature available
- Available in 44-pin SOJ package and 44-pin TSOP(II)

### DESCRIPTION

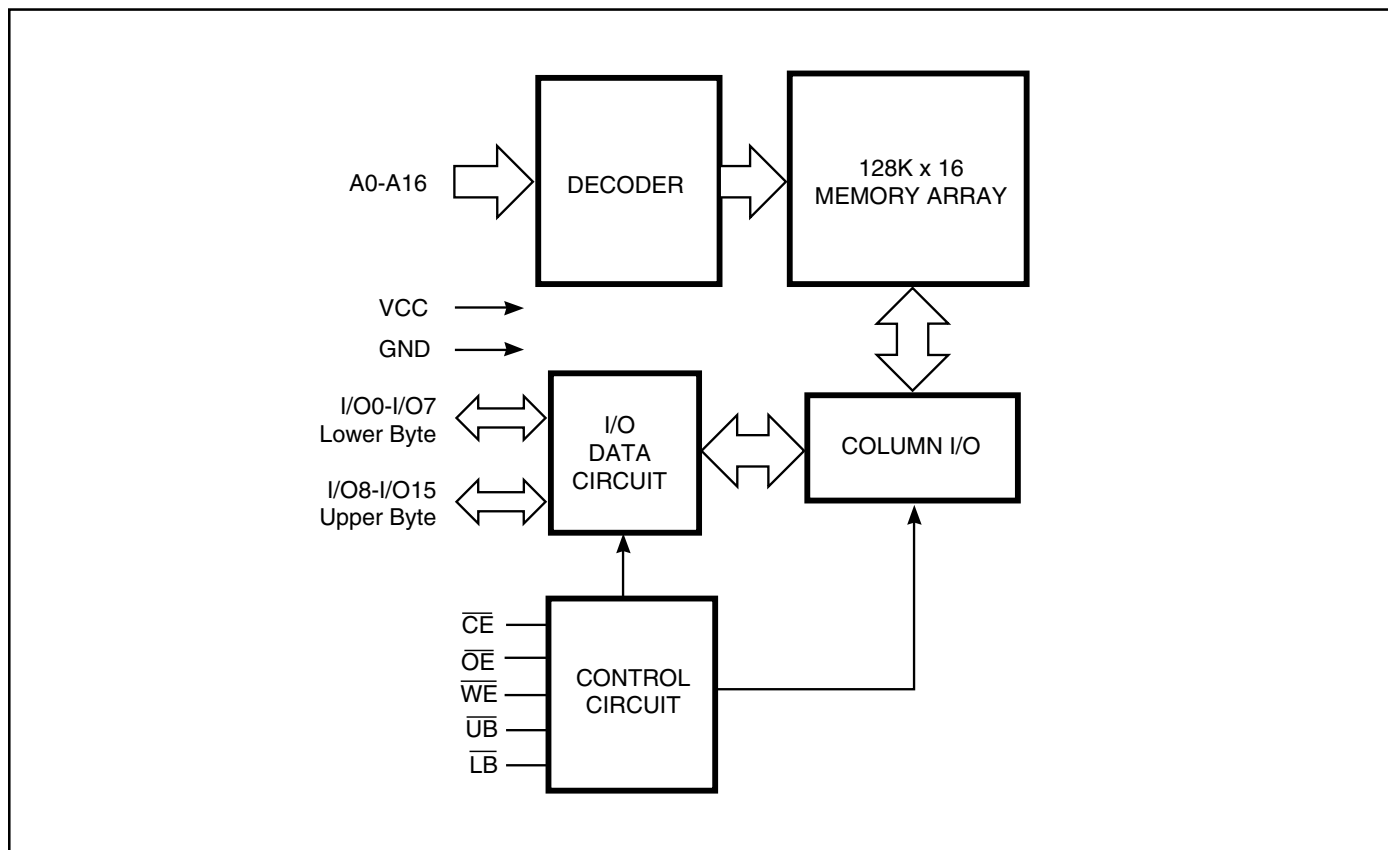
The *ISSI* IS61C12816 is a high-speed, 2,097,152-bit static RAM organized as 131,072 words by 16 bits. It is fabricated using *ISSI's* high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields access times as fast as 12 ns with low power consumption.

When  $\overline{CE}$  is HIGH (deselected), the device assumes a standby mode at which the power dissipation can be reduced down with CMOS input levels.

Easy memory expansion is provided by using Chip Enable and Output Enable inputs,  $\overline{CE}$  and  $\overline{OE}$ . The active LOW Write Enable ( $\overline{WE}$ ) controls both writing and reading of the memory. A data byte allows Upper Byte ( $\overline{UB}$ ) and Lower Byte ( $\overline{LB}$ ) access.

The IS61C12816 is packaged in the JEDEC standard 44-pin 400-mil SOJ and 44-pin TSOP(II).

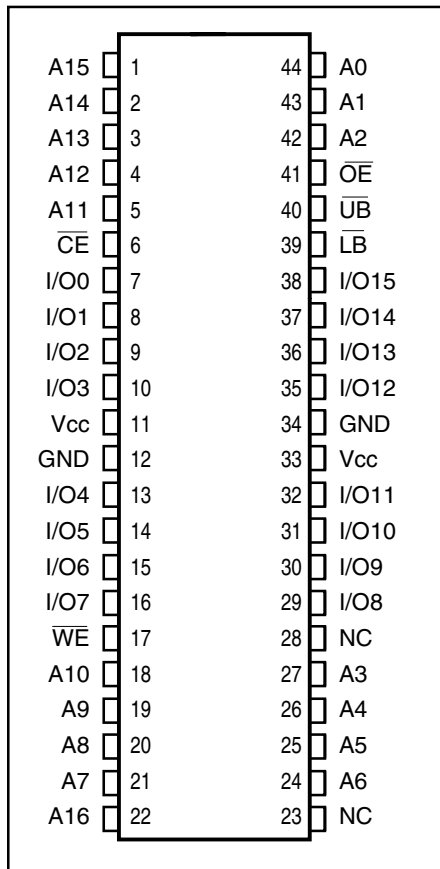
### FUNCTIONAL BLOCK DIAGRAM



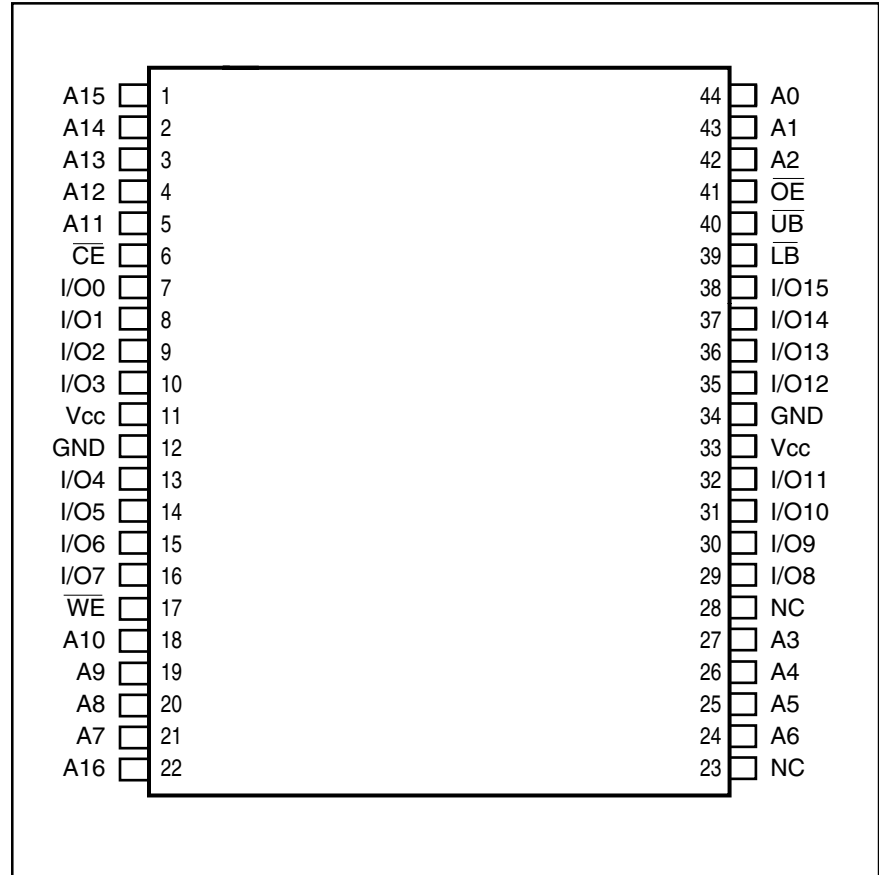
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## PIN CONFIGURATIONS

## 44-Pin SOJ



## 44-Pin TSOP(II)



## PIN DESCRIPTIONS

A0-A16	Address Inputs	$\overline{LB}$	Lower-byte Control (I/O0-I/O7)
I/O0-I/O15	Data Inputs/Outputs	$\overline{UB}$	Upper-byte Control (I/O8-I/O15)
$\overline{CE}$	Chip Enable Input	NC	No Connection
$\overline{OE}$	Output Enable Input	Vcc	Power
$\overline{WE}$	Write Enable Input	GND	Ground

## TRUTH TABLE

Mode	I/O PIN						Vcc Current	
	$\overline{WE}$	$\overline{CE}$	$\overline{OE}$	$\overline{LB}$	$\overline{UB}$	I/O0-I/O7		I/O8-I/O15
Not Selected	X	H	X	X	X	High-Z	High-Z	Isb1, Isb2
Output Disabled	H	L	H	X	X	High-Z	High-Z	Icc1, Icc2
	X	L	X	H	H	High-Z	High-Z	
Read	H	L	L	L	H	DOUT	High-Z	Icc1, Icc2
	H	L	L	H	L	High-Z	DOUT	
	H	L	L	L	L	DOUT	DOUT	
Write	L	L	X	L	H	DIN	High-Z	Icc1, Icc2
	L	L	X	H	L	High-Z	DIN	
	L	L	X	L	L	DIN	DIN	

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

Symbol	Parameter	Value	Unit
V <sub>TERM</sub>	Terminal Voltage with Respect to GND	-0.5 to +7.0	V
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C
P <sub>T</sub>	Power Dissipation	1.5	W
I <sub>OUT</sub>	DC Output Current (LOW)	20	mA

**Note:**

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**OPERATING RANGE**

Range	Ambient Temperature	Speed	V <sub>CC</sub>
Commercial	0°C to +70°C	-12	5V ± 5%
		-15, -20	5V ± 10%
Industrial	-40°C to +85°C	-12	5V ± 5%
		-15, -20	5V ± 10%

**DC ELECTRICAL CHARACTERISTICS** (Over Operating Range)

Symbol	Parameter	Test Conditions	Min.	Max.	Unit
V <sub>OH</sub>	Output HIGH Voltage	V <sub>CC</sub> = Min., I <sub>OH</sub> = -4.0 mA	2.4	—	V
V <sub>OL</sub>	Output LOW Voltage	V <sub>CC</sub> = Min., I <sub>OL</sub> = 8.0 mA	—	0.4	V
V <sub>IH</sub>	Input HIGH Voltage		2.2	V <sub>CC</sub> + 0.5	V
V <sub>IL</sub>	Input LOW Voltage <sup>(1)</sup>		-0.5	0.8	V
I <sub>LI</sub>	Input Leakage	GND - V <sub>IN</sub> - V <sub>CC</sub>	-2	2	μA
I <sub>LO</sub>	Output Leakage	GND - V <sub>OUT</sub> - V <sub>CC</sub> , Outputs Disabled	-2	2	μA

**Notes:**

1. V<sub>IL</sub> (min.) = -3.0V for pulse width less than 10 ns.

**POWER SUPPLY CHARACTERISTICS<sup>(1)</sup>** (Over Operating Range)

Symbol	Parameter	Test Conditions	-12		-15		0		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
I <sub>CC</sub>	V <sub>CC</sub> Dynamic Operating Supply Current	V <sub>CC</sub> = Max., I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub>	Com.	280	—	260	—	235	mA
			Ind.	—	300	—	290	—	
I <sub>SB1</sub>	TTL Standby Current (TTL Inputs)	V <sub>CC</sub> = Max., V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> $\overline{CE} \cdot V_{IH}$ , f = 0	Com.	—	50	—	50	—	mA
			Ind.	—	55	—	55	—	
I <sub>SB2</sub>	CMOS Standby Current (CMOS Inputs)	V <sub>CC</sub> = Max., $\overline{CE} \cdot V_{CC} - 0.2V$ , V <sub>IN</sub> = V <sub>CC</sub> - 0.2V, or V <sub>IN</sub> - 0.2V, f = 0	Com.	—	10	—	10	—	mA
			Ind.	—	15	—	15	—	

**Note:**

1. At f = f<sub>MAX</sub>, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

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## CAPACITANCE<sup>(1)</sup>

Symbol	Parameter	Conditions	Max.	Unit
C <sub>IN</sub>	Input Capacitance	V <sub>IN</sub> = 0V	6	pF
C <sub>OUT</sub>	Input/Output Capacitance	V <sub>OUT</sub> = 0V	8	pF

**Note:**

1. Tested initially and after any design or process changes that may affect these parameters.

## READ CYCLE SWITCHING CHARACTERISTICS<sup>(1)</sup> (Over Operating Range)

Symbol	Parameter	-12		-15		-20		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>RC</sub>	Read Cycle Time	12	—	15	—	20	—	ns
t <sub>AA</sub>	Address Access Time	—	12	—	15	—	20	ns
t <sub>OH</sub>	Output Hold Time	3	—	3	—	4	—	ns
t <sub>ACE</sub>	$\overline{CE}$ Access Time	—	12	—	15	—	20	ns
t <sub>DOE</sub>	$\overline{OE}$ Access Time	—	6	—	7	—	9	ns
t <sub>HZOE</sub> <sup>(2)</sup>	$\overline{OE}$ to High-Z Output	—	6	0	6	0	8	ns
t <sub>LZOE</sub> <sup>(2)</sup>	$\overline{OE}$ to Low-Z Output	0	—	0	—	0	—	ns
t <sub>HZCE</sub> <sup>(2)</sup>	$\overline{CE}$ to High-Z Output	0	6	0	6	0	8	ns
t <sub>LZCE</sub> <sup>(2)</sup>	$\overline{CE}$ to Low-Z Output	3	—	3	—	3	—	ns
t <sub>BA</sub>	$\overline{LB}$ , $\overline{UB}$ Access Time	—	6	—	7	—	9	ns
t <sub>HZB</sub>	$\overline{LB}$ , $\overline{UB}$ to High-Z Output	0	6	0	6	0	8	ns
t <sub>LZB</sub>	$\overline{LB}$ , $\overline{UB}$ to Low-Z Output	0	—	0	—	0	—	ns

**Notes:**

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured ±500 mV from steady-state voltage. Not 100% tested.
3. Not 100% tested.

## AC TEST CONDITIONS

Parameter	Unit
Input Pulse Level	0V to 3.0V
Input Rise and Fall Times	3 ns
Input and Output Timing and Reference Level	1.5V
Output Load	See Figures 1 and 2

## AC TEST LOADS

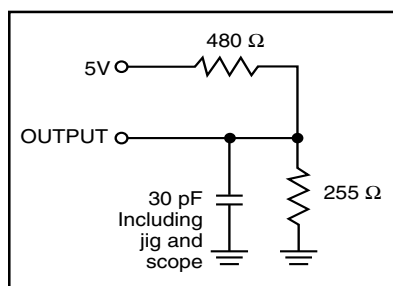


Figure 1

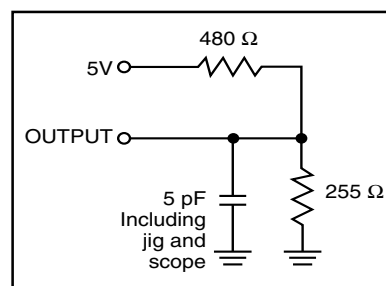
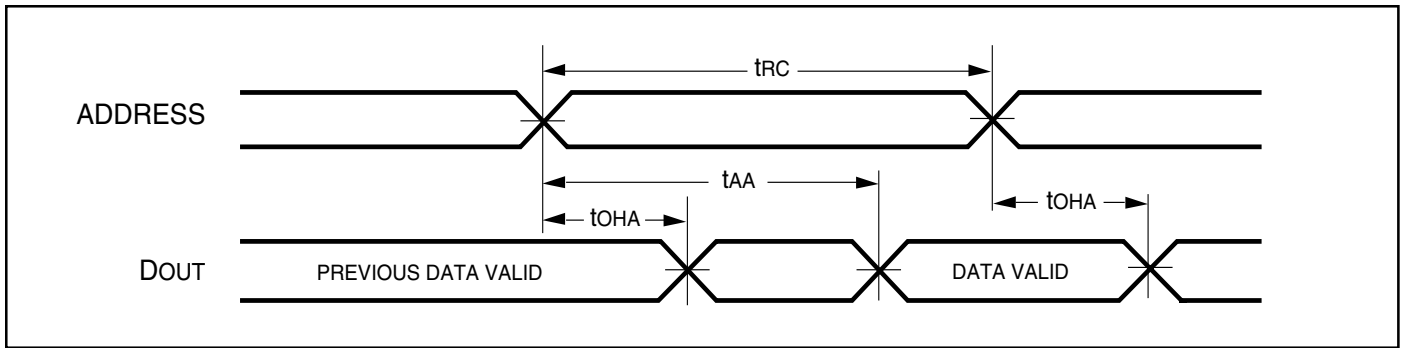


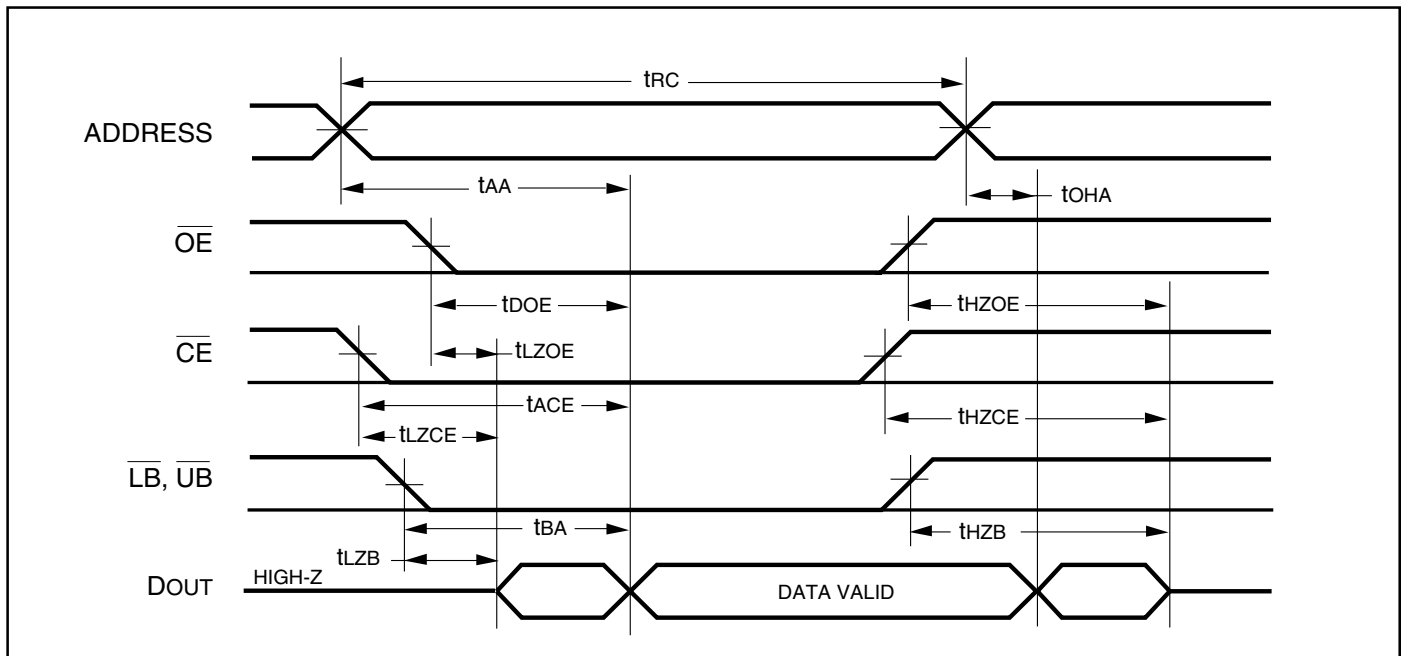
Figure 2

AC WAVEFORMS

READ CYCLE NO. 1<sup>(1,2)</sup> (Address Controlled) ( $\overline{CE} = \overline{OE} = V_{IL}$ ,  $\overline{UB}$  or  $\overline{LB} = V_{IL}$ )



READ CYCLE NO. 2<sup>(1,3)</sup>



Notes:

1.  $\overline{WE}$  is HIGH for a Read Cycle.
2. The device is continuously selected.  $\overline{OE}$ ,  $\overline{CE}$ ,  $\overline{UB}$ , or  $\overline{LB} = V_{IL}$ .
3. Address is valid prior to or coincident with  $\overline{CE}$  LOW transition.

**WRITE CYCLE SWITCHING CHARACTERISTICS<sup>(1,3)</sup>** (Over Operating Range)

Symbol	Parameter	-12		-15		-20		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>WC</sub>	Write Cycle Time	12	—	15	—	20	—	ns
t <sub>SCE</sub>	$\overline{CE}$ to Write End	9	—	10	—	12	—	ns
t <sub>AW</sub>	Address Setup Time to Write End	9	—	10	—	12	—	ns
t <sub>HA</sub>	Address Hold from Write End	0	—	0	—	0	—	ns
t <sub>SA</sub>	Address Setup Time	0	—	0	—	0	—	ns
t <sub>PWB</sub>	$\overline{LB}$ , $\overline{UB}$ Valid to End of Write	9	—	10	—	12	—	ns
t <sub>PWE</sub>	$\overline{WE}$ Pulse Width	9	—	10	—	12	—	ns
t <sub>SD</sub>	Data Setup to Write End	6	—	7	—	9	—	ns
t <sub>HD</sub>	Data Hold from Write End	0	—	0	—	0	—	ns
t <sub>HZWE<sup>(2)</sup></sub>	$\overline{WE}$ LOW to High-Z Output	—	6	—	7	—	9	ns
t <sub>LZWE<sup>(2)</sup></sub>	$\overline{WE}$ HIGH to Low-Z Output	3	—	3	—	3	—	ns

**Notes:**

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of  $\overline{CE}$  LOW and  $\overline{UB}$  or  $\overline{LB}$ , and  $\overline{WE}$  LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.



**ORDERING INFORMATION****Commercial Range: 0°C to +70°C**

Speed (ns)	Order Part No.	Package
12	IS61C12816-12T	Plastic TSOP(II)
12	IS61C12816-12K	400-mil Plastic SOJ
15	IS61C12816-15T	Plastic TSOP(II)
15	IS61C12816-15K	400-mil Plastic SOJ
20	IS61C12816-20T	Plastic TSOP(II)
20	IS61C12816-20K	400-mil Plastic SOJ

**Industrial Range: -40°C to +85°C**

Speed (ns)	Order Part No.	Package
12	IS61C12816-12TI	Plastic TSOP(II)
12	IS61C12816-12KI	400-mil Plastic SOJ
15	IS61C12816-15TI	Plastic TSOP(II)
15	IS61C12816-15KI	400-mil Plastic SOJ
20	IS61C12816-20TI	Plastic TSOP(II)
20	IS61C12816-20KI	400-mil Plastic SOJ

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